IPC ASSOCIATION ELECTRONIC	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All r international and Pan-American copyright convention			all rights reserved un	This document der both level parts,	document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
1752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				Form Type * Distribute	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				ials and Mfg Information				
Supplier	Information													
Company name*			Company unique ID			Unique ID Authority				Response Date*				
onsemi						I				2024-05-1	2024-05-11			
Contact N	ame		Title - Contact			Phone - Contact*				Email - Contact*				
Product-E	Env-Stewards		Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
uthorize	d Representative*		Title - Representative			Phone - Representative*			Email - R	Email - Representative*				
Product-Env-Stewards			Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
	Requester Item Number Mfr I		m Number Mfr Item Name			Effective I	Date Ve	ersion	Manufacturing Site	W	eight*	UOM	Unit Type	
		NID9N05BCLT4G 9 A, 52 V, N-Chan MOSFET w/ESD I		nel, Logic Level Clamped Protection	2024-05-1	1	VN5		35	50.99	mg	Each		
Manufa	cturing Proccess Informa	ntion												
	Terminal Plating / Grid Array Material Terminal Ba			l Base Alloy J-STD-020 MSL Rating			Peak Process Body Temperature Max Time at Peak				Temperature Number of Reflow Cycles			
Matte Tin (Sn) - annealed CU Alloy 1				260		C	30	second	3					
Comments														
evel 1 - m	aximum time at peak temperat	ure during sol	dering is 10-3	0 seconds										
or more i	information regarding material	l composition j	please refer to	page 3										

RoHS Material Composition Declaration			Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified above. If a homogeneous material within the part contains a representation in this paragraph. If the Company and the Supplier is liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement											
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required f Requester) and click on Submit Form to ha		Accepted" on the Supplier Acceptance drop-dow	n. This will display the signature area. Digita	lly sign the declaration (if required by the							
Supplier Digital Signature Ra	astislav Drska	-En									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.2	mg	Supplier	Silicon (Si)	7440-21-3		0.2	mg
Die Attach	1.4	mg	A	Lead (Pb)	7439-92-1	7a	1.33	mg
			Supplier	Tin (Sn)	7440-31-5		0.07	mg
Lead Frame	214.64	mg	В	Nickel (Ni)	7440-02-0		0.4293	mg
			Supplier	Copper (Cu)	7440-50-8		214.2107	mg
Mold Compound-Black	129.65	mg		Epoxy resin	proprietary data		9.0755	mg
			Supplier	Phenolic Resin	Proprietary Data		3.8895	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		12.965	mg
			Supplier	Carbon Black (C)	1333-86-4		0.6482	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		103.0717	mg
Plating	3.73	mg	Supplier	Tin (Sn)	7440-31-5		3.73	mg
Wire Bond - Al	1.37	mg	Supplier	Aluminum (Al)	7429-90-5		1.37	mg